

WHAT IS CLAIMED IS:

1. A manufacturing method of an electron-emitting device comprising the steps of:

5 disposing an electrically conductive member having a second gap on a substrate; and

applying a voltage to said electrically conductive member while irradiating at least said second gap with an electron beam from electron emitting means disposed apart from said electrically conductive member in an
10 atmosphere comprising a carbon compound.

2. A manufacturing method of an electron-emitting device comprising the steps of:

15 disposing first and second electrically conductive members on a substrate with a second gap interposed; and

applying a voltage to said first and second electrically conductive members while irradiating at least said second gap with an electron beam from
20 electron emitting means disposed apart from said electrically conductive members in an atmosphere comprising a carbon compound.

3. A manufacturing method of an electron-emitting device comprising the steps of:

25 disposing an electrically conductive member having a second gap on a substrate; and

irradiating at least said second gap with an
electron beam from electron emitting means disposed
apart from said electrically conductive member in an
atmosphere comprising a carbon compound within a period
5 where a voltage is applied to said electrically
conductive member.

4. A manufacturing method of an electron-emitting
device comprising the steps of:

10 disposing first and second electrically conductive
members on a substrate with a second gap interposed;
and

irradiating at least said second gap with an
electron beam from electron emitting means disposed
15 apart from said electrically conductive members in an
atmosphere comprising a carbon compound within a period
where a voltage is applied to said first and second
electrically conductive members.

20 5. The manufacturing method of an electron-
emitting device according to claim 1 or 3, wherein said
electrically conductive member having said second gap
is an electrically conductive film which connects a
pair of electrodes to each other and has said second
25 gap in a portion of the electrically conductive film.

6. The manufacturing method of an

electron-emitting device according to claim 2 or 4,
wherein said electrically conductive members are a pair
of electrodes which are disposed with said second gap
interposed.

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7. The manufacturing method of an electron-
emitting device according to claim 2 or 4, wherein said
electrically conductive members are a first
electrically conductive film and a second electrically
10 conductive film which are connected to a first and
second electrodes apart disposed respectively and are
disposed with said second gap interposed.

8. The manufacturing method of an electron-
15 emitting device according to any one of claims 1
through 4, wherein said applied voltage is a pulse like
voltage.

9. The manufacturing method of an electron-
20 emitting device according to any one of claims 1
through 4, wherein said electron beam is at an energy
level not lower than 1 keV and not higher than 20 keV.

10. A manufacturing method of an electron source
25 having a plurality of electron-emitting devices,
wherein said electron-emitting device is manufactured
by the manufacturing method according to any one of

claims 1 through 4.

11. A manufacturing method of an image-forming
apparatus having an electron source and an image
5 forming member, wherein said electron source is
manufactured by the manufacturing method according to
claim 10.

12. An electron-emitting device having a carbon
10 film, wherein said carbon film has specific resistance
not higher than 0.001 Ωm .

13. An electron source having a plurality of
electron-emitting devices, wherein said electron-
15 emitting device is the electron-emitting device
according to claim 12.

14. An image-forming apparatus having an electron
source and an image forming member, wherein said
20 electron source is the electron source according to
claim 13.